

Japanese Patent Laid-Open No.H8-88305

[0011]

This embodiment has used a copper plating solution as the plating solution 14, but it goes without saying that to enhance the strength of the metal foil, it is possible to use a nickel plating solution with 500 g/L of nickel sulfamate as the main ingredient of the plating solution 14 or an iron plating solution with 400 g/L of iron sulfate, 50 g/L of sodium chloride and 30 g/L of aqua regia.